

METHOD AND APPARATUS FOR THREE DIMENSIONAL INSPECTION OF

ELECTRONIC COMPONENTS

ABSTRACT OF THE DISCLOSURE

5 A three dimensional inspection method for inspecting ball
array devices having a plurality of balls, where the ball array
device is positioned in an optical system. The inspection method
includes the steps of illuminating at least one ball on the ball
array device, and disposing a sensor, a first optical element and
a second optical element in relation to the ball array device so
10 that the sensor obtains at least two differing views of the at
least one ball, the sensor providing an output representing the
at least two differing views. The output is processed using a
triangulation method to calculate a three dimensional position of
the at least one ball with reference to a pre-calculated
15 calibration plane.

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